

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (cancelled)

1 **Claim 2 (currently amended):** The electronic component
2 mounting method according to claim 5 [[1]], further
3 comprising the step of:
4 feed-forward controlling a detected result of the
5 printing position of the solder paste from the step of
6 detecting to the step of mounting,
7 wherein the detected result is an output at the step
8 of detecting.

Claims 3-4 (cancelled)

1 **Claim 5 (currently amended):** An electronic component
mounting method for mounting an electronic component The
electronic component mounting method according to claim 1,
4 further comprising the steps of:
5 providing a circuit board further comprising a land;
6 dividing the circuit board into a plurality of blocks;
7 printing a solder paste on the land;

8 detecting a printing position of the solder paste on
9 the circuit board;
10 mounting the electronic component on the circuit board
11 by referring to the printing position of the solder paste
12 as a reference;
13 obtaining a shift amount between a position of the
14 land corresponding to the electronic component to be
15 mounted in each block and the printing position of the
16 solder paste for the land; and
17 setting a target mounting position of the electronic
18 component for each block based on the shift amount thus
19 obtained.

1 Claim 6 (original): The electronic component mounting
2 method according to claim 5,
3 wherein the blocks are obtained by an annular division
4 from a peripheral edge of the circuit board toward a
5 center.

1 Claim 7 (original): The electronic component mounting
2 method according to claim 5,
3 wherein the blocks are obtained by dividing the
4 circuit board like a lattice.

1 Claim 8 (currently amended): An electronic component
2 mounting method for mounting an electronic component ~~The~~
3 ~~electronic component mounting method according to claim 1,~~
4 further comprising the steps of:
5 providing a circuit board further comprising a land;
6 printing a solder paste on the land;
7 detecting a printing position of the solder paste on
8 the circuit board;
9 mounting the electronic component on the circuit board
10 by referring to the printing position of the solder paste
11 as a reference;
12 deciding a self-alignment effect from a shift state
13 between a position of a land corresponding to the
14 electronic component to be mounted and the printing
15 position of the solder paste for the land;
16 setting a target mounting position of the electronic
17 component by using the printing position of the solder
18 paste as a reference in a case that the self-alignment
19 effect is great; and
20 setting the target mounting position by using the
21 position of the land as the reference in a case that the
22 self-alignment effect is small.

1 Claim 9 (currently amended): An electronic component
2 mounting method for mounting an electronic component ~~The~~
3 ~~electronic component mounting method according to claim 1,~~
4 further comprising the steps of:

5 providing a circuit board further comprising a land;
6 printing a solder paste on the land;
7 detecting a printing position of the solder paste on
8 the circuit board;
9 mounting the electronic component on the circuit board
10 by referring to the printing position of the solder paste
11 as a reference;

12 setting a correction value at an optional rate for a
13 shift amount between a position of a land corresponding to
14 the electronic component to be mounted and the printing
15 position of the solder paste for the land; and

16 changing a target mounting position of the electronic
17 component from the position of the land toward the printing
18 position of the solder paste based on the correction value
19 thus set.

1 Claim 10 (original): The electronic component
2 mounting method according to claim 9,
3 wherein the correction value is set based on a degree
4 of the self-alignment effect which is determined depending

5 on a shift state between the position of the land
6 corresponding to an electronic component to be mounted and
7 the printing position of the solder paste for the land.

1 Claim 11 (original): The electronic component
2 mounting method according to claim 9,
3 wherein the correction value is set depending on a
4 characteristic of a solder paste to be used.

1 Claim 12 (currently amended): The electronic
2 component mounting method according to claim 8 [[1]],
3 wherein the step of mounting is not carried out in the
4 case that the electronic component interferes with adjacent
5 other electronic components on the circuit board.

1 Claim 13 (currently amended): The electronic
2 component mounting method according to claim 8 [[1]],
3 further comprising the step of:

4 changing the a target mounting position of the
5 electronic component to be mounted toward the position of
6 the land and from the printing position of the solder paste
7 to a position in which the interference is not present in
8 the case that the electronic component interferes with
9 adjacent other electronic components on the circuit board.

1 Claim 14 (currently amended) : An electronic component
2 mounting method for mounting an electronic component The
3 electronic component mounting method according to claim 1,
4 further comprising the steps of:
5 providing a circuit board further comprising a land;
6 dividing the circuit board into a plurality of blocks;
7 printing a solder paste on the land;
8 detecting a printing position of the solder paste on
9 the circuit board;
10 mounting the electronic component on the circuit board
11 by referring to the printing position of the solder paste
12 as a reference;
13 obtaining a shift amount in a direction of rotation
14 and a shift amount in a horizontal direction in the case
15 that a shift amount of a position of the land corresponding
16 to the electronic component to be mounted from the printing
17 position of the solder paste for the land exceeds a
18 predetermined shift amount, and
19 setting a target mounting position and a target
20 rotating angle of the electronic component based on the
21 shift amounts in the horizontal direction and the direction
22 of rotation.

1 Claim 15 (currently amended): The electronic
2 component mounting method according to claim 8 [[1]],
3 wherein the step of detecting includes the steps of:
4 picking up an image of a circuit board having a solder
5 paste printed thereon;
6 reproducing a shape of a land hidden in the solder
7 paste by interpolating the picked-up image with referring
8 previously registered land data; and
9 obtaining a center of a position of the land from the
10 shape of the land thus reproduced.

Claims 16-30 (cancelled)